



# i.MX RT700 Crossover MCU with Arm® Cortex®-M33, NPU, DSP and GPU Cores

## i.MX-RT700

### Preproduction

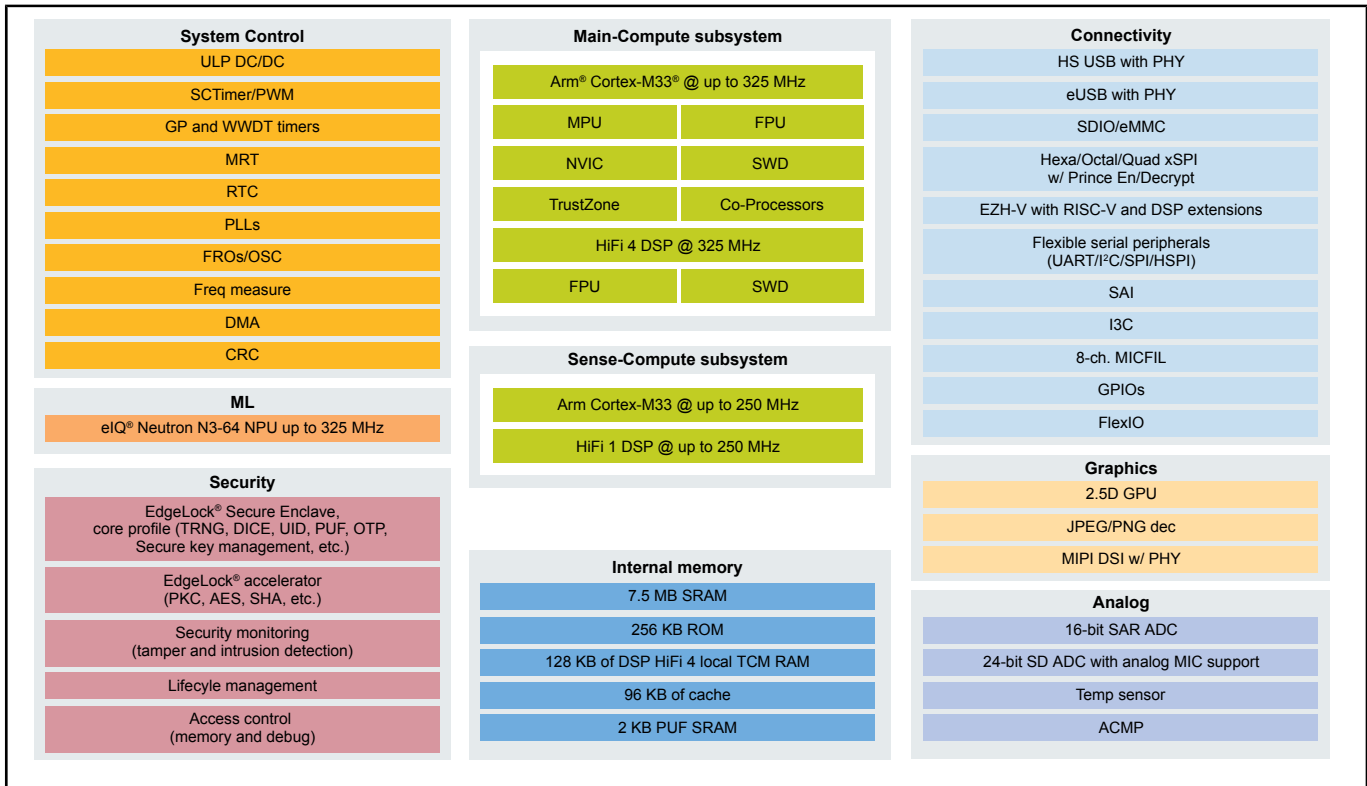
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The i.MX RT700 features up to five computing cores designed to power smart AI-enabled edge devices such as wearables, consumer medical, smart home and HMI devices. Its Compute Subsystem includes a primary Arm® Cortex®-M33 running at 325 MHz and Cadence® Tensilica® HiFi 4 DSP for more DSP and audio processing. An ultra-low power Sense Subsystem includes a second Arm Cortex-M33 and Cadence Tensilica HiFi 1 DSP. This removes the need for an external sensor hub reducing system design complexity, footprint and BOM costs. i.MX RT700 includes NXP's [eIQ® Neutron NPU](#) accelerating AI workloads by up to 172x and integrates up to 7.5 MB of onboard SRAM.

The i.MX RT700 is supported by the [MCUXpresso Developer Experience](#), which includes an SDK, a choice of IDEs and secure provisioning and configuration tools to enable rapid development.

# i.MX RT700 Crossover MCU Block Diagram



View additional information for [i.MX RT700 Crossover MCU with Arm® Cortex®-M33, NPU, DSP and GPU Cores.](#)

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